

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6023537

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TOMOHIRO YAMANAKA	03/16/2020
YOICHI MAKIMOTO	03/16/2020
RECEIVING PARTY DATA	
Name:	SANSHA ELECTRIC MANUFACTURING CO., LTD.
Street Address:	3-1-56, NISHIAWAJI, HIGASHIYODOGAWA-KU
Internal Address:	OSAKA-SHI
City:	OSAKA
State/Country:	JAPAN
Postal Code:	533-0031
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29728654
CORRESPONDENCE DATA	
Fax Number:	(540)428-1720
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	LUKE A. KILYK
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Address Line 2:	KILYK & BOWERSOX, P.L.L.C.
Address Line 4:	WARRENTON, VIRGINIA 20186
ATTORNEY DOCKET NUMBER:	3151-020
NAME OF SUBMITTER:	LUKE A. KILYK
SIGNATURE:	/luke a kilyk/
DATE SIGNED:	03/20/2020
Total Attachments: 2	
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source=Assignment_3151_020#page2.tif	

Docket No.

SOLE/JOINT INVENTION

ASSIGNMENT

(Worldwide Rights)

WHEREAS WE/I, the below named inventor(s) [hereinafter referred to as Assignor(s)], have made an invention entitled:

Semiconductor device

for which We/I filed an application for United States Letters patent on _____, as U.S. Patent Application No. _____, and

WHEREAS, Sansha Electric Manufacturing Co., Ltd. of JAPAN, whose post office address is 3-1-56, Nishiawaji, Higashiyodogawa-ku, Osaka-shi Osaka 533-0031, Japan (hereby referred to as Assignee), are desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for good and valuable consideration the receipt of which from assignee is hereby acknowledged, We/I, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, our entire right, title, and interest in and to this invention and this application, any applications claiming priority or benefit to this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and We/I hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE/I HEREBY covenant that We/I have the full right to convey the interest assigned by this Assignment, and We/I have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE/I HEREBY further covenant and agree that We/I will, without further consideration, communicate with assignee, its successors and assigns, any facts known to us/me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

IN TESTIMONY WHEREOF, We/I have hereunto set our hands.

FULL NAME OF INVENTOR: YAMANAKA Tomohiro
Address: c/o Sansha Electric Manufacturing Co., Ltd., 3-1-56, Nishiawaji, Higashiyodogawa-ku, Osaka- shi Osaka 533-0031, Japan
Signature: YAMANAKA Tomohiro
Date: March 16, 2020

Docket No.

SOLE/JOINT INVENTION

ASSIGNMENT

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WHEREAS WE/I, the below named inventor(s) [hereinafter referred to as Assignor(s)], have made an invention entitled:

Semiconductor device

for which We/I filed an application for United States Letters patent on _____, as U.S. Patent Application No. _____, and

WHEREAS, Sansha Electric Manufacturing Co., Ltd. of JAPAN, whose post office address is 3-1-56, Nishiawaji, Higashiyodogawa-ku, Osaka-shi Osaka 533-0031, Japan (hereby referred to as Assignee), are desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for good and valuable consideration the receipt of which from assignee is hereby acknowledged, We/I, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, our entire right, title, and interest in and to this invention and this application, any applications claiming priority or benefit to this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and We/I hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE/I HEREBY covenant that We/I have the full right to convey the interest assigned by this Assignment, and We/I have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE/I HEREBY further covenant and agree that We/I will, without further consideration, communicate with assignee, its successors and assigns, any facts known to us/me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

IN TESTIMONY WHEREOF, We/I have hereunto set our hands.

FULL NAME OF INVENTOR: MAKIMOTO Yoichi	
Address: c/o Sansha Electric Manufacturing Co., Ltd., 3-1-56, Nishiawaji, Higashiyodogawa-ku, Osaka-shi Osaka 533-0031, Japan	
Signature:	<i>Y. Makimoto</i>
Date:	<i>Mar. 16, 2020</i>